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| 부천대UI | **Partner Information Form****Student Exchange Program 2022, Fall Semester** |
| **Please write down with as much detail as possible. All documents should be written in English or Korean** |
| **University Name** | Asia Pacific University of Technology & Innovation  |
| **Address** | Technology Park MalaysiaBukit Jalil, Kuala Lumpur 57000Malaysia |
| **Website** | http://www.apu.edu.my |
| **Number of students can be accepted in 2019, spring semester** | 2 |
| **Application Deadline** | 2 months before the intake |
| **Recommended arrival dates and time** | One week before the commencement of class  | **Name of airport** | KLIA Termina 1 / KLIA Terminal 2 |
| **Airport pick-up service** | [ / ] YES  | **Service price** | Waived  |
| [ ] No |  |
| **Orientation date** | 21 Sep 2022 |
| **Semester dates** | 21 Sep 2022 |
| **Recommended** **departure dates and time** | One week before the commencement of class |
| **Required language proficiency** | Subject to requirement set by Bucheon University |
| **Area of study or course not available** | Available to all course |
| **Visa requirements** | Student Visa |
| **Accommodation (with as much detail as possible)** | Refer to attached accommodation forms. |
| **Insurance** | Medical Insurance covered with EMGS |
| **Other Fees (with as much detail as possible)** | **Visa Application & Processing Fee**1. Payable upon acceptance of Letter RM 3,400 / USD 875 2. International Student Registration & Administrative Fee RM 4,600/ USD 1180 3. Personal Bond (Refundable) RM 1,000 /USD 2604. Library Deposit (Refundable) RM 500 / USD 128 |
| **Contact** | Name: Lee Ai MunPhone number: +603-8996-1000Mobile number: +012-3300576 |
| **Required documents** | 1. Passport copies all pages including blank pages (Clearly see the page numbers)
2. Passport-size Photo (Necessarily comply with given guidelines)
3. Latest Academic Qualification
4. Letter of Declaration health status from student
5. Reference letter for student from Bucheon University
6. Filled Application form
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